

CLIPPEDIMAGE= JP359105349A

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TITLE: INTEGRATED CIRCUIT DEVICE

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INVENTOR-INFORMATION:

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NAME

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ABSTRACT:

PURPOSE: To enable to manufacture an integrated circuit substrate which has many terminals and complicated functions with a small area and good yield at a low cost by a method wherein electrode terminals on the integrated circuit substrate are so arranged that the interval between connection members becomes almost constant.

CONSTITUTION: A pad d<SB>7</SB> is set at the center of one side. Next, the value of a wire interval l is set at a value which satisfies the condition of wire bonding, pads d<SB>5</SB> and d<SB>8</SB> are decided by drawing a

triangle whose bottom side is a wire  $C_{7}$  and height is 1. Further, pads  $d_{5}$  and  $d_{9}$  are decided by drawing a triangle whose bottom side is wires  $C_{6}$  and  $C_{8}$  and height is 1. The pads  $d_{1}$ ~ $d_{13}$  are arranged in the above-mentioned manner, the value of the interval  $l$  is set again by evaluating its result, and the optimum arrangement is made by successive approximation with a computer. For example, the arrangement of 13 bonding pads  $d_{1}$ ~ $d_{13}$  is made on one side of a chip, and, based on the optimum value, the pad intervals are successively enlarged toward each corner from the center of one side of the chip; thereby enabling the arrangement in such a manner that each wire interval becomes almost constant.

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